

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Confirmation No. 4175

Hideo HADA et al.

Docket No. 2001-1787A

Serial No. 09/996,676

Group Art Unit 1752

Filed November 30, 2001

Examiner R. Ashton

POSITIVE-WORKING PHOTORESIST COMPOSITION

THE COMMISSIONER IS AUTHORIZED TO CHARGE ANY DEFICIENCY IN THE FEES FOR THIS PAPER TO DEPOSIT ACCOUNT NO. 23-0975

SUPPLEMENTAL RESPONSE

Assistant Commissioner for Patents, Washington, D.C. 20231

Sir:

Further to the response filed on November 18, 2002, please further amend the present application as follows:

IN THE CLAIMS:

Please amend claim 12 as follows:

- 12. (Amended) A positive-working photoresist composition which comprises, as a uniform solution in an organic solvent:
- (A) 100 parts by weight of a resinous compound capable of being imparted with increased solubility in an aqueous alkaline solution by interaction with an acid;
- (B) from 0.5 to 30 parts by weight of a radiation-sensitive acid generating compound capable of generating an acid by irradiation with a radiation; and
 - (C) an organic solvent in an amount sufficient to dissolve the components (A) and (B), the component (A) being a copolymer consisting of the monomeric units of
- (a1) from 30 to 60% by moles of 2-alkyl-2-adamantyl (meth) acrylate units having the formula:

